

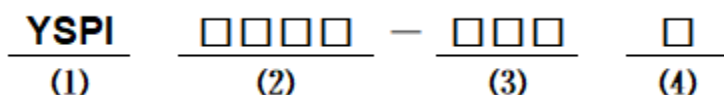
■ Features

- Molding Inductor.
- Low Profile, Low Temp.
- Large Current (Over 15A).
- Customize For Different Need.
- Operating temperature: $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$.

■ Applications

- General Electronic.
- Video Device, TV, TFT.
- Power Module for PC.
- NB/Lap Top Computer.
- Server, VGA Card/Module.

■ Product Identification



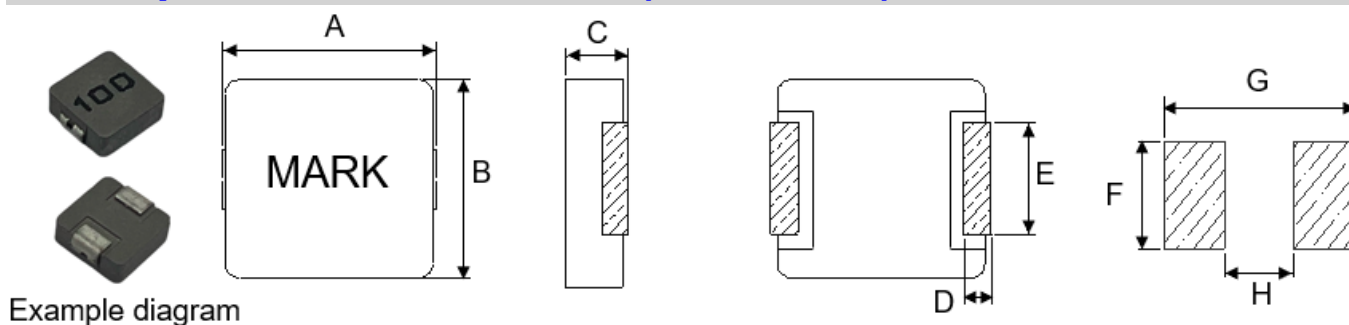
(1) : Type

(2) : Dimensions

(3) : Inductance value

(4) : Inductance Tolerance: N=±30%, M=±20%, K=±10%

■ Shapes and Dimensions (Unit: mm)



TYPE	A	B	C Max.	D	E	F Ref.	G Ref.	H Ref.
YSPI0850	8.7±0.3	8.1±0.2	5.0	2.0±0.3	3.0±0.2	3.2	9.0	4.7

■ YSPI0850 Series

Part Number	Inductance (uH) @100KHz/1V	DCR Max. (mΩ)	Saturation Current Isat Typ.(A)	Heat Rating Current Irms Typ.(A)
YSPI0850-R33M	0.33±20%	1.5	35.0	30.0
YSPI0850-1R0M	1.0±20%	5.5	18.0	16.0
YSPI0850-1R5M	1.5±20%	6.0	16.0	13.0
YSPI0850-2R2M	2.2±20%	13.0	15.0	10.0
YSPI0850-3R3M	3.3±20%	18.0	13.0	8.0
YSPI0850-4R7M	4.7±20%	22.0	11.0	7.5
YSPI0850-6R8M	6.8±20%	25.0	10.0	7.0
YSPI0850-100M	10±20%	45.0	7.0	6.0
YSPI0850-150M	15±20%	60.0	5.5	5.0
YSPI0850-220M	22±20%	90.0	5.0	4.0
YSPI0850-330M	33±20%	130	4.0	3.3
YSPI0850-470M	47±20%	200	3.0	2.5
YSPI0850-680M	68±20%	300	3.0	2.0
YSPI0850-101M	100±20%	350	2.7	1.5

※ All test data is referenced to 25 °C ambient.

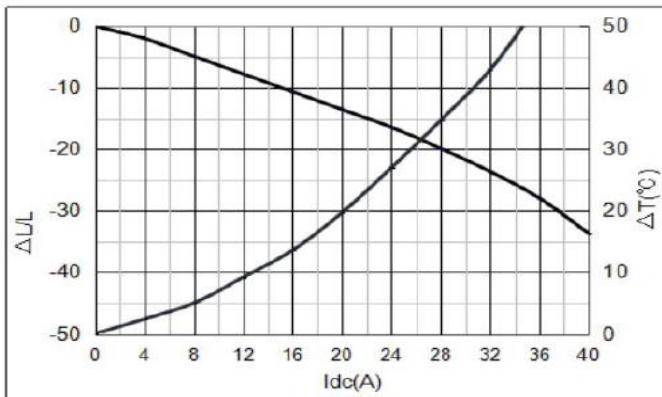
※ Irms (A):DC current (A) that will cause an approximate ΔT of 40 °C(reference ambient temperature is 25 °C)

※ Isat(A):DC current (A) that will cause L0 to drop approximately 30%.(Internal control standards at 40% MAX)

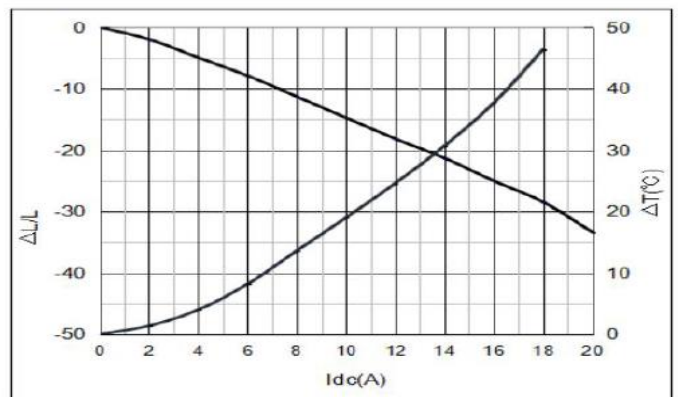
※ Absolute maximum voltage 30VDC.

Current Characteristic

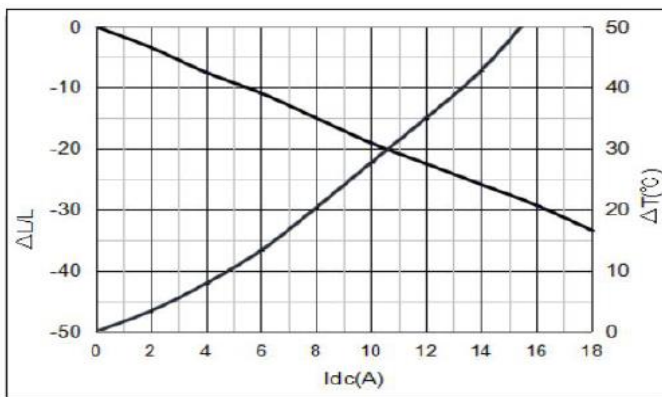
YSPI0850-R33M



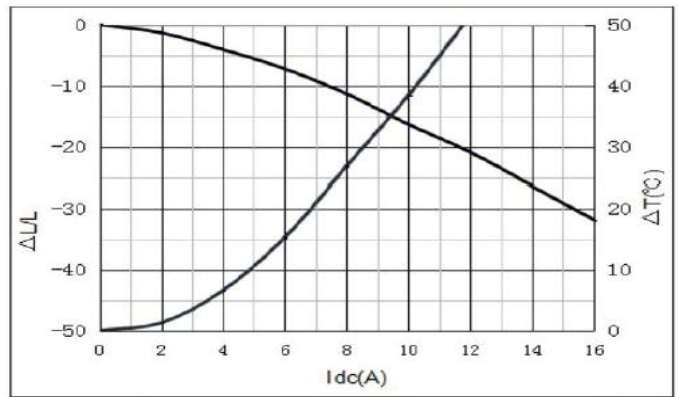
YSPI0850-1R0M



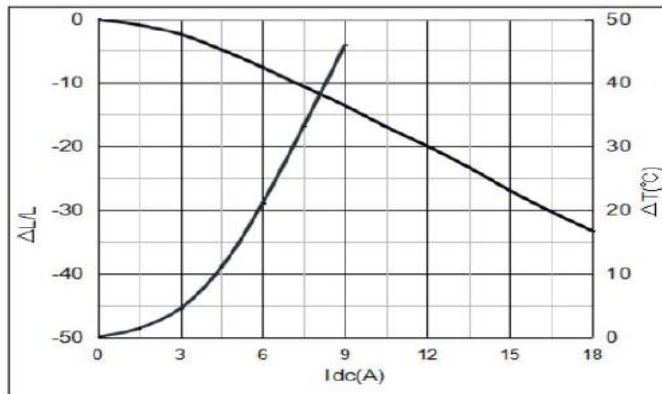
YSPI0850-1R5M



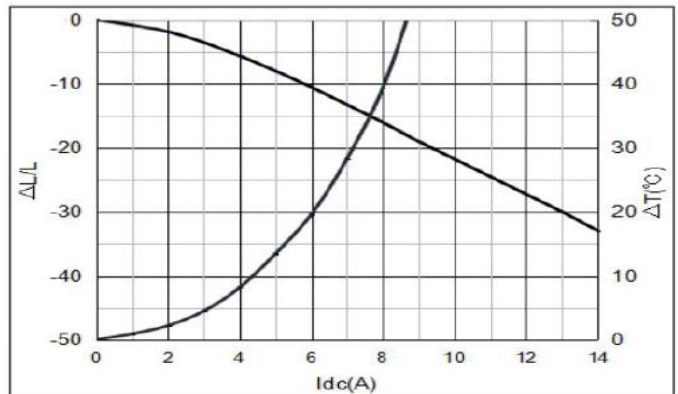
YSPI0850-2R2M



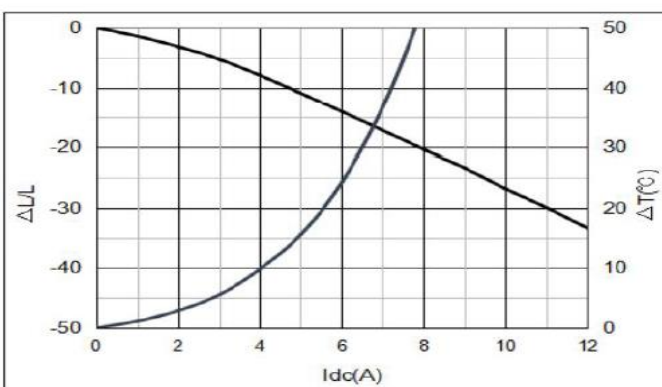
YSPI0850-3R3M



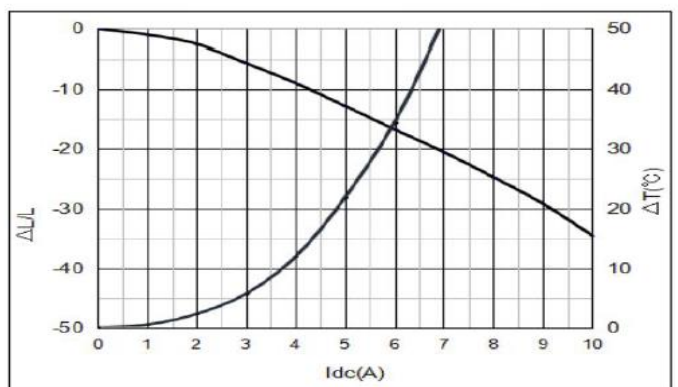
YSPI0850-4R7M



YSPI0850-6R8M

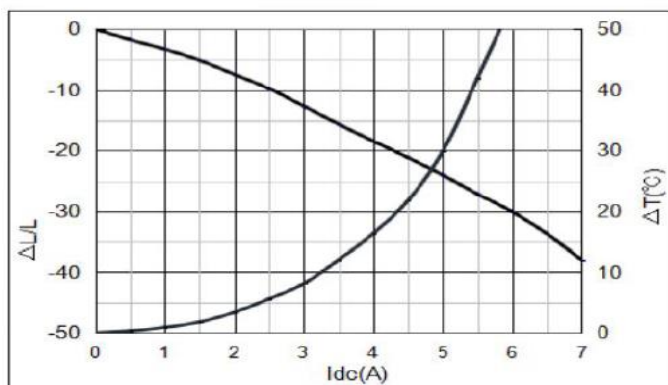


YSPI0850-100M

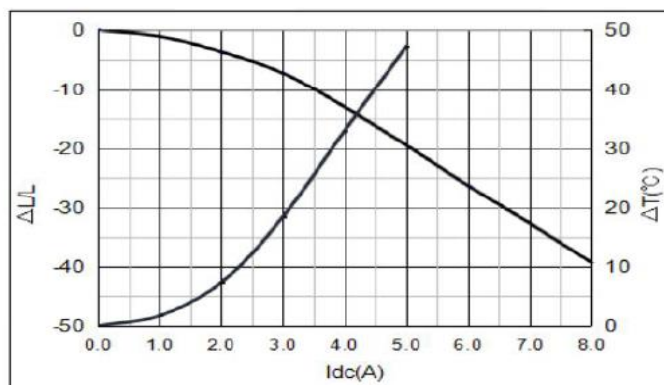


■ Current Characteristic

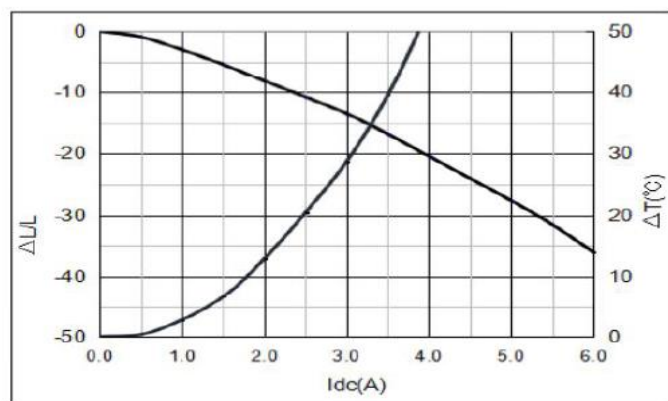
YSPI0850-150M



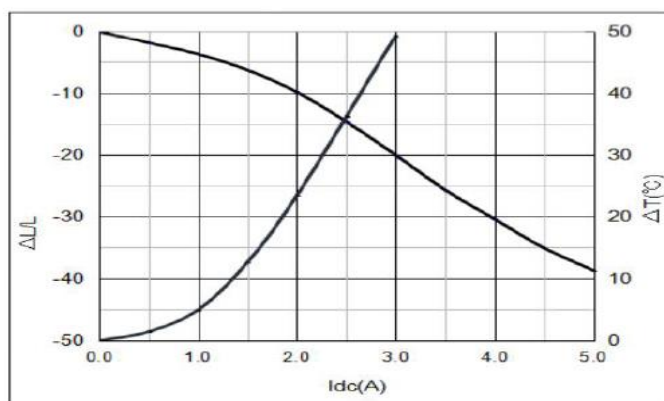
YSPI0850-220M



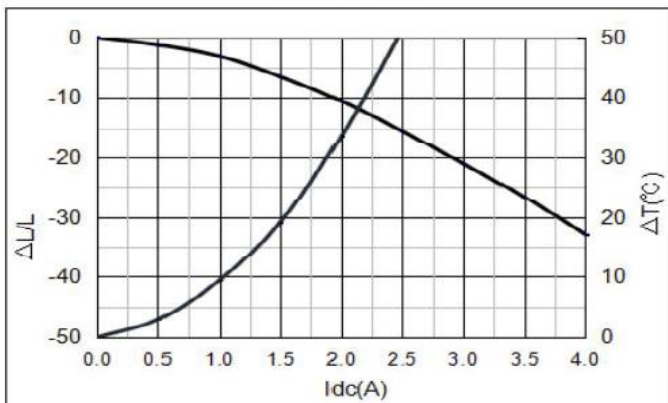
YSPI0850-330M



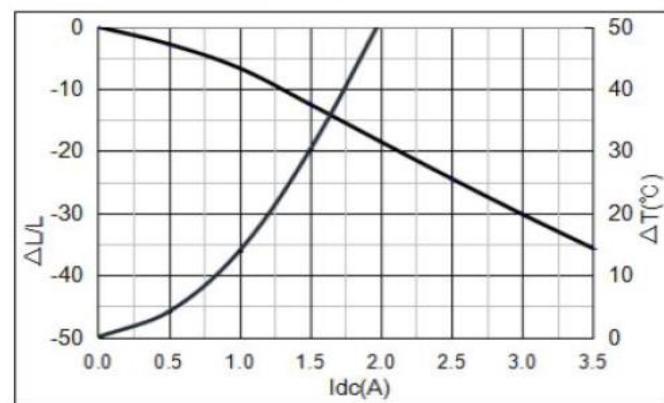
YSPI0850-470M



YSPI0850-330M



YSPI0850-101M



General Characteristics

NO.	ITEMS	CONDITIONS	SPECIFICATION
1	OPERATION TEMPERATURE STORAGE TEMPERATURE		-40 ~ +125 °C (INCLUDING COIL TEMPERATURE RISE) -40 ~ +125 °C
2	TEMPERATURE COEFFICIENT	-30 ~ +105 °C	0 ~ 2000ppm/°C
3	FIXING STRENGTH	SAMPLE IS PUSHED IN THREE DIRECTIONS OF X, Y AND Z WITH FORCE OF 5. 0N FOR 10±5 SECONDS. AFTER SOLDERING BETWEEN COPPER PLATE AND ELECTRODES.	NO ELECTRODE DETACHMENT.
4	RESISTANCE TO SOLDERING HEAT TEST	REFER TO THE SPEC "STD-001NP".	NO MECHANICAL BREAKAGE. DEVIATION RELATIVE TO INITIAL VALUE: L: WITHIN ±10%
5	SOLDERABILITY TEST	IMMERSE THE ELECTRODE IN FLUX FOR 5 SECONDS. THEN DIP THE ELECTRODE INTO A SOLDERING BATH OF 245±5 °C FOR 2±0.5 SECONDS.	OVER 95% OF THE SURFACE BEING IMMersed SHALL BE COVERED WITH NEW SOLDER UNIFORMLY.
6	VIBRATION TEST	AMPLITUDE: 1.5mm P-P FREQUENCY: 10~55~10Hz (1 MINUTE PER CYCLE) DURATION: 1 HOUR IN EACH OF X, Y, Z AXIS.	DEVIATION RELATIVE TO INITIAL VALUE: L: WITHIN ±10%
7	HUMIDITY TEST	TEMPERATURE: 40 °C ± 2 °C HUMIDITY: 90%~95%RH DURATION: 96±4 HOURS.	DEVIATION RELATIVE TO INITIAL VALUE: L: WITHIN ±10%
8	THERMAL SHOCK TEST	20 CYCLES OF +105 °C FOR 30 MINUTES, -40 °C FOR 30 MINUTES. CHARACTERISTICS ARE MEASURED AFTER THE AMBIENT AIR EXPOSURE OF 1 HOUR	DEVIATION RELATIVE TO INITIAL VALUE: L: WITHIN ±10%
9	HIGH TEMPERATURE STORAGE TEST	TEMPERATURE: 125 °C ± 2 °C DURATION: 96±4 HOURS	
10	LOW TEMPERATURE STORAGE TEST	TEMPERATURE: -40 °C ± 3 °C DURATION: 96±4 HOURS.	

* Standard testing conditions:

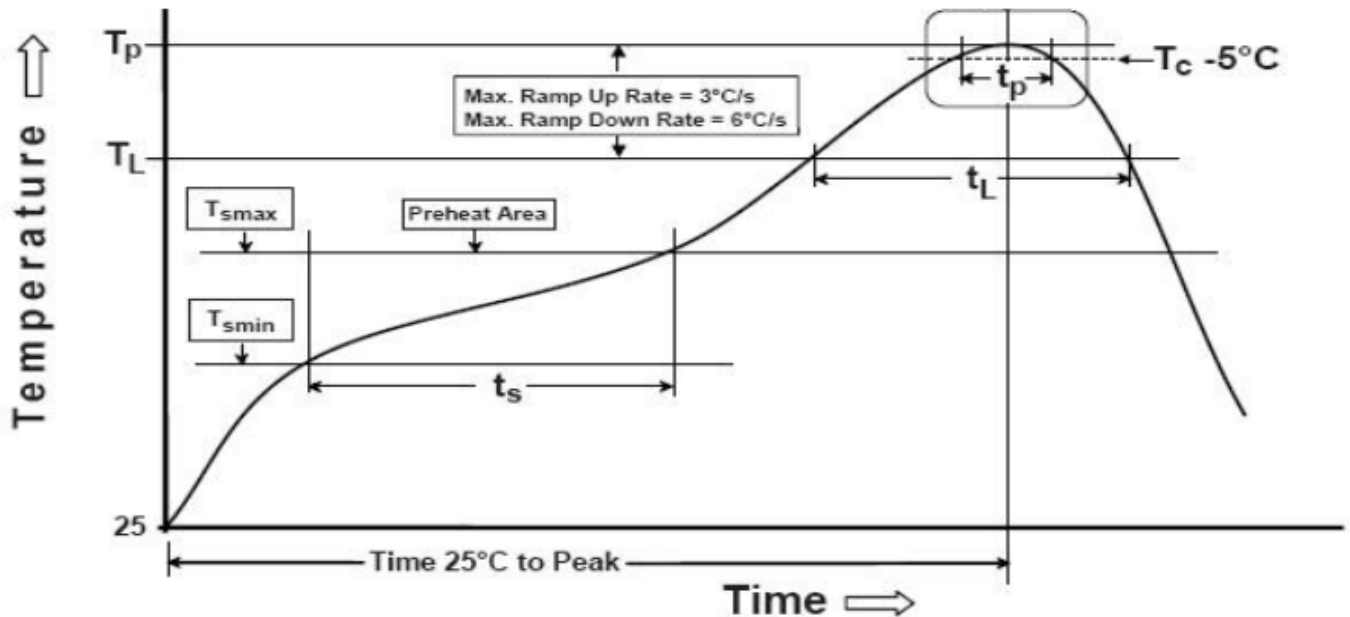
Unless otherwise specified, the standard range of atmospheric conditions for measurements and tests are as follows:

Ambient temperature: 15 °C ~ 35 °C. Relative humidity : 25% ~ 85%. Air pressure: 86kPa ~ 106kPa.

If there is doubt about the results, measurement shall be made within the following limits:

Ambient temperature: 20 °C ± 1 °C. Relative humidity: 63% ~ 67%. Air pressure: 86kPa ~ 106kPa.

Reflow profile for SMT components



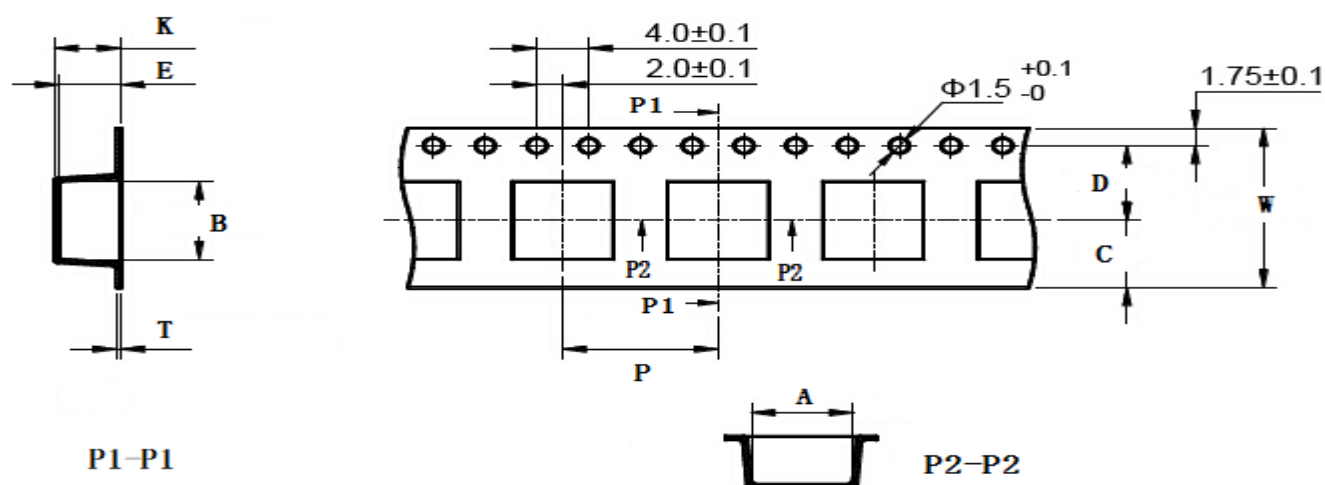
Reflow is referred to standard IPC/ JEDEC J-STD-020D

Profile Feature		Lead(Pb) Free solder
Preheat and soak	• temperature Min.(Ts min)	150°C
	• temperature Max.(Ts max)	200°C
	• time(Tsmin to Ts max)(ts)	60-120 Seconds
Average ramp up rate Tsmax to Tp		3°C/Second Max.
Liquidous temperature (T_L)		217 °C
Time (T_L) maintained above T_L		60-150 seconds
Peak package body temperature (T_p)		Table2
Time (t_p)* within 5 °C of the specified classification temperature (T_c)		30* seconds
Average Ramp-down rate (T_p to T_L)		6 °C/second max
Time 25 °C to peak temperature		8 minutes max.

Table2. Pb-Free Process - Classification Temperatures (T_c)

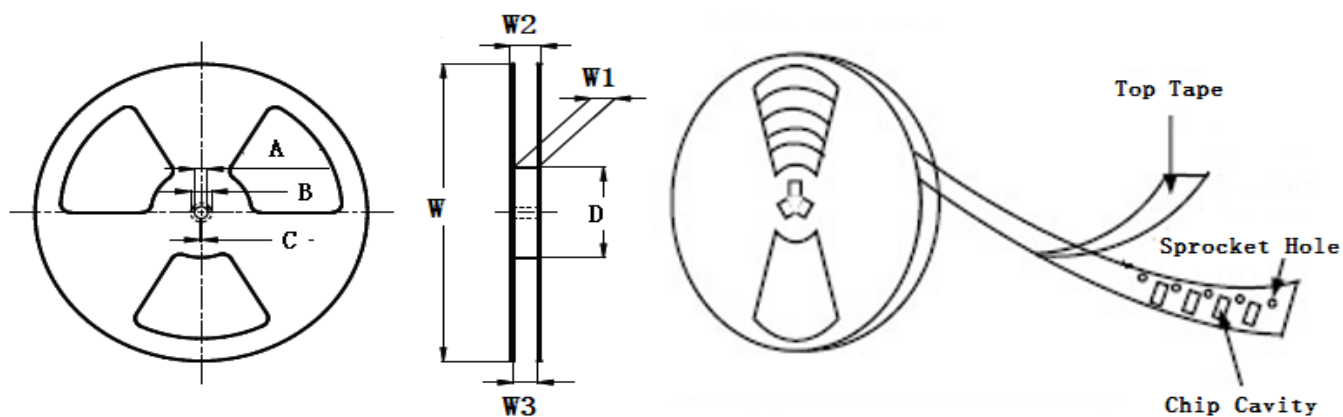
Package Thickness	Volume mm3 <350	Volume mm3 350~2000	Volume mm3 >2000
<1.6 mm	260°C	260°C	260°C
1.6mm- 2.5mm	260°C	250°C	245°C
>2.5 mm	250°C	245°C	245°C

Taping Dimensions(Unit:mm)



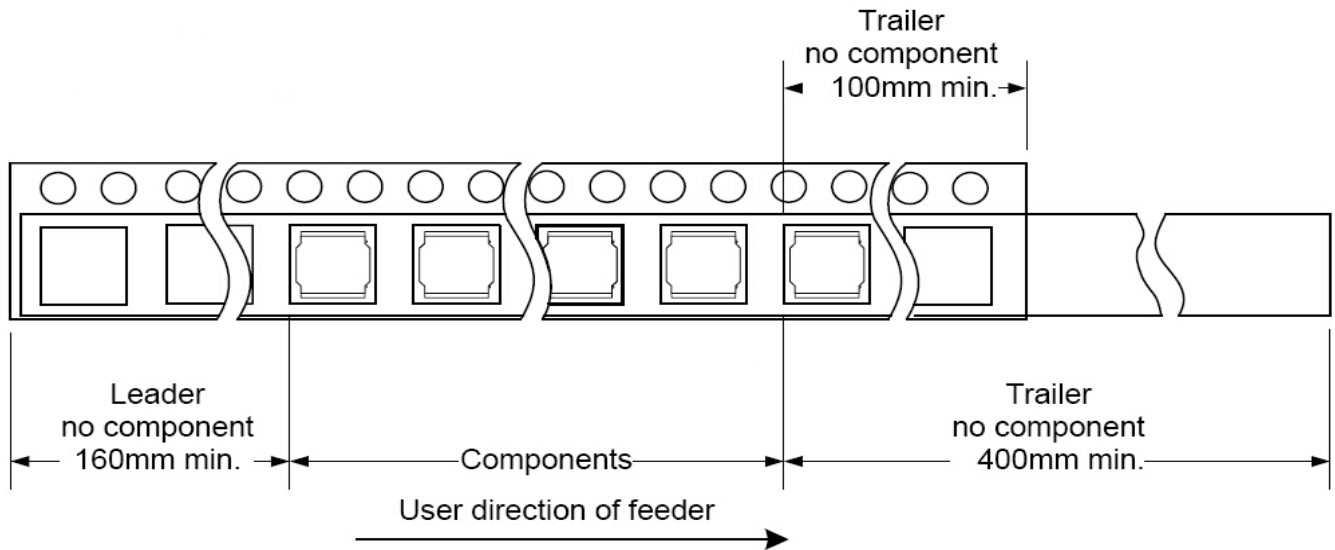
TYPE	W	A	B	C	D	E	P	K Ref	T	MPQ
YSPI0850	24±0.3	8.9±0.1	10.±0.1	10.75	11.5±0.1	4.4±0.1	16.0±0.1	4.5	0.35±0.05	1000

Reel Dimensions(Unit:mm)

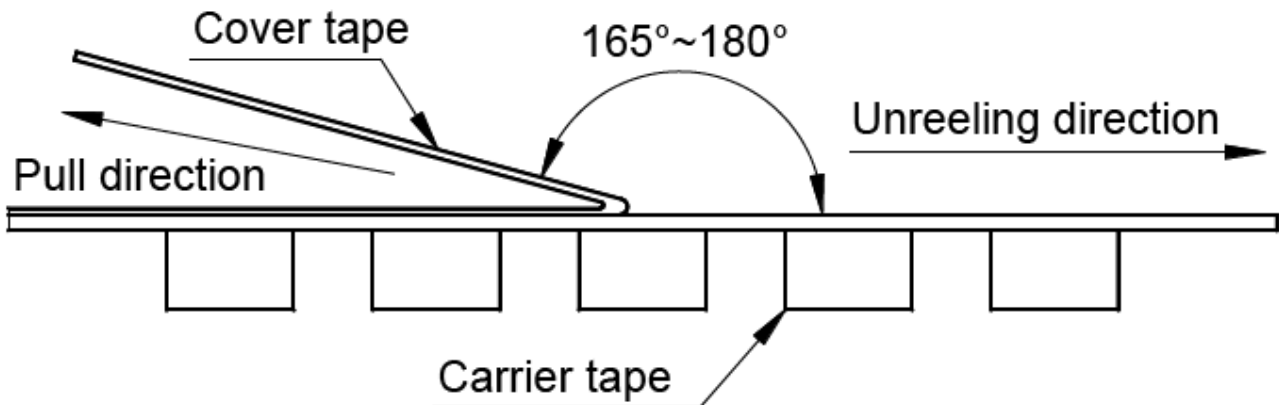


TYPE	W	W1	W2	W3	A	B	C	D
YSPI0850	330±2.0	24.4±2.0	30.4MAX	23.9 Min	13.0±0.5	21.0±0.8	2.0±0.5	100 Min

■ Direction of rolling



■ Cover tape peel off condition



Cover tape peel force shall be 0.1N to 1.3N.

Reference peel speed 300±10mm/min.